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Maser Engineering - 2D and 3D Non Destructive Analysis for electronic components and modules

Monday 23 April 2018 16:40 (20 minutes)

Speaker: Kees Revenberg
Abstract: This presentation is about new Non Destructive Analysis (NDA) techniques in the first level Failure Analysis flow for electronic components and modules. With unclear defect locations F/A engineers prefer to start with NDA steps avoiding removal or interfering with the root cause defects. MASER Engineering will present its NDA capabilities on Electrical, XRAY, SAM, LIT and EOTPR analysis. All techniques give valuable information about the defect and help in the decision process entering the next (destructive) steps. More and more electronic components become 3D System in Package designs, concentrating complex assembly and materials in a small enclosure. After an update of modern IC package assembly complexity, each of the five analysis steps will be shown with real application examples.

Presenter: REVENBERG, Kees

Session Classification: Technologies from Academia